

## 概述 Introduction

由雅时国际商讯ACT International主办出版的《半导体科技 SST-AP China》杂志已经创刊逾10年。2011年《半导体科技》将出版6期（双月刊）。《半导体科技》获得世界知名品牌杂志《Solid State Technology》和《Advanced Packaging》的版权许可，独家以简体中文翻译其内容并出版和发行。

《半导体科技》提供半导体业界最新新闻、信息、深度分析和权威评论。每期杂志印刷出版9,000册，同时发行网络版电子杂志和在线杂志网站，为中国半导体行业专家、工程师和技术工程经理，提供决策和采购需要的最新技术、市场资讯及商业采购信息。

《半导体科技》覆盖半导体制造、先进封装、晶圆代工、集成电路、薄膜微电子、平板显示器、纳米技术、工艺及设备等内容。

《半导体科技》服务于整个半导体供应链，包括经销商、制造商、代工厂、行业协会或联盟、研发组织、混合电路、专用ASIC、半导体制造和测试设备、材料、IC封装，以及政府及教育机构。

Established for more than 10 years, SST-AP China magazine -- published by ACT International - will be produced six times (bi-monthly) in 2011. SST-AP China has been granted an exclusive license by world-renowned titles Solid State Technology and Advanced Packaging to translate and circulate editorial content in a simplified Chinese edition.

Through our publication we provide the latest semiconductor news, in-depth analysis and authoritative commentary. Each issue of SST-AP China will have a print run of 9,000 copies supplemented by the web-based e-magazine and online operation, providing our qualified China semiconductor professionals with the business and product information they need to make informed purchasing decisions.

SST-AP China covers semiconductor manufacturing, advanced packaging, wafer fabrication, integrated circuits, thin-film microelectronics, flat-panel displays, and nanometer technologies, processes and equipment and more.

The publication serves the entire semiconductor supply chain which includes merchant and captive manufacturers, foundries, consortiums, R&D operations, hybrid circuits, ASICs, semiconductor manufacturing and test equipment, materials, IC packaging, as well as government and educational institutions.

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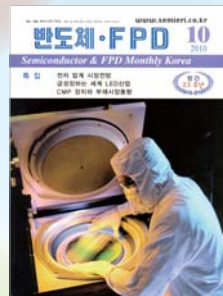
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